What is claimed is:

1. A resist composition generating an acid upon light exposure and having solubility in a developing solution, which is changed by action of an acid, the resist composition comprising:

a base material component (A) having solubility in a developing solution, which is changed by action of an acid; and

a polyethylene glycol having a weight-average molecular weight of 1000 or more,

wherein a content of the polyethylene glycol is 0.8 to 32 parts by mass with respect to 100 parts by mass of the base material component (A).

2. The resist composition according to claim 1, further comprising:

an acid generator component (B) generating an acid upon exposure,

wherein the acid generator component (B) contains a compound (B1) including an onium salt.

3. A method of forming a resist pattern, comprising:

a step of forming a resist film on a supporting body using the resist composition according to Claim 1 or 2;

a step of light-exposing the resist film; and

a step of developing the exposed resist film to form a resist pattern.